

# xLED

## xLED-22530 Passive Pin Fin Heatsink $\Phi$ 225mm

### Features VS Benefits

- \* Mechanical compatibility with direct mounting of the SMD products to the LED cooler and thermal performance matching the lumen packages.
- \* For flood light, street light and high bay designs from 5,000 to 12,000 lumen.
- \* Thermal resistance range Rth 0.63°C/W.
- \* Product size: Diameter 225mm - Standard height 30mm, Other widths on request.
- \* Forged from highly conductive aluminium for optimal thermal performance (AL1070), aluminium 1070 thermal conductivity is 2.0 times higher than ADC12.
- \* 2 standard colors - clear anodised - black anodised
- \* Waterproof level designs from IP65 to IP67.
- \* With the SMD products (3030, 2835, 5050.....): Bridgelux, Cree, Edison, Citizen, LG Innotek, Lumileds, Luminus, Lumens, Nichia, Osram, Prolight Opto, Seoul, Samsung, Sharp.



### The LED engine and radiator assembly directly Mounting Options

- \* Below you find an overview of SMD products which standard fit on the xLED series coolers.
- \* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED coolers.

### Waterproof connectors & Driver



Not only consider waterproofness of the lens, but also on outside connecting line. Mingfa Tech can provide compatible waterproof connector with xLED heat sink.

Features :

- The claws and seals excellent design, can hold cable firmly and have a wider cable range. Resistant to salt water, weak acid, alcohol, oil, grease and common solvency.
- 1. Working temperature: Min -40°C to Max 120°C.
- 2. Body material: Brass nickel plated.
- 3. Cable range Dia: 3-6mm.
- 4. Protection degree: IP68

Mingfa tech product number:

- 21000001-04 (M8)
- 21000002-04 (M10)

With the Drivers.

- MEAN WELL:
  - HBG-160 Series; HBG-240 Series;
- INVENTRONICS:
  - EUR-150Sxxx Series; EUR-200Sxxx Series; EUR-240Sxxx Series;

### Order Information

Example: xLED-22530-B

Example: xLED-22530 - **1**

**1** Anodising Color

B-Black

C-Clear

Z-Custom

#### Notes:

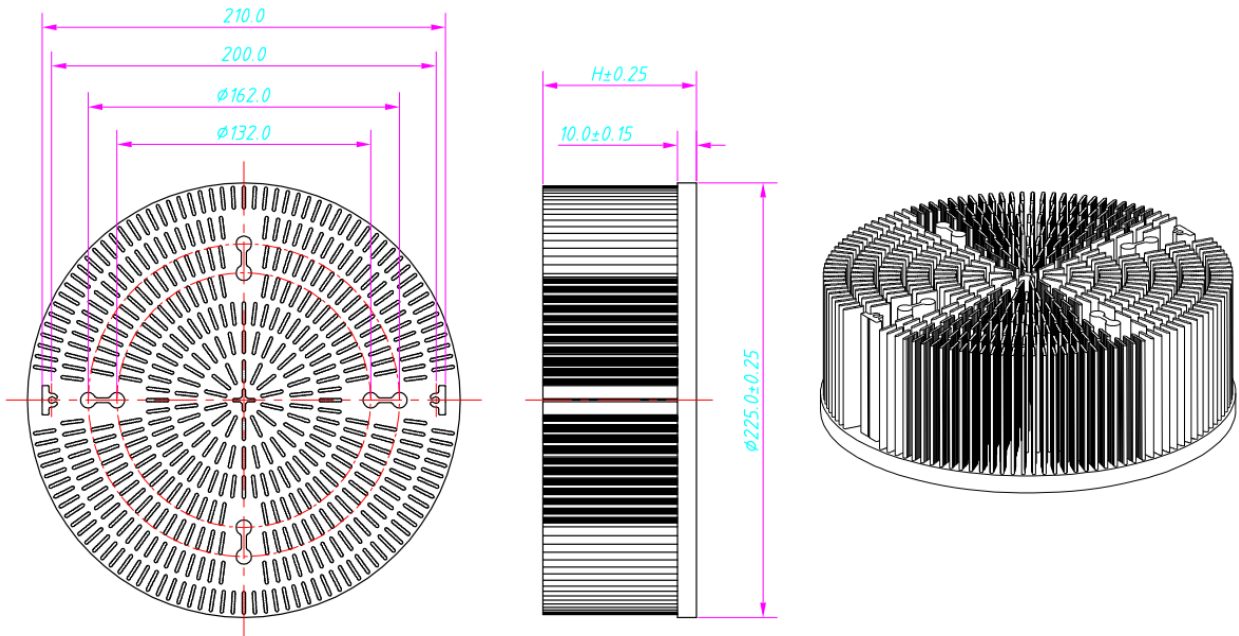
- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications



**xLED**

**xLED-22530 Passive Pin Fin Heatsink  $\Phi$ 225mm**

**Drawings & Dimensions**



**Product deta table**

	<p><b>xLED</b></p>
<b>Model No.</b>	<b>xLED-22530</b>
<b>Heatsink Size</b>	<b><math>\Phi</math>225xH30mm</b>
<b>Heatsink Material</b>	<b>AL1070</b>
<b>Finish</b>	<b>Black Anodized</b>
<b>Weight (Kg)</b>	<b>1.53</b>
<b>Dissipated power (T<sub>hs</sub>-amb,50°C)</b>	<b>80.0 (W)</b>
<b>Cooling surface area (mm<sup>2</sup>)</b>	<b>321495</b>
<b>Thermal Resistance (R<sub>hs</sub>-amb)</b>	<b>0.63 (°C/W)</b>

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## xLED-22530 Passive Pin Fin Heatsink $\Phi 225\text{mm}$

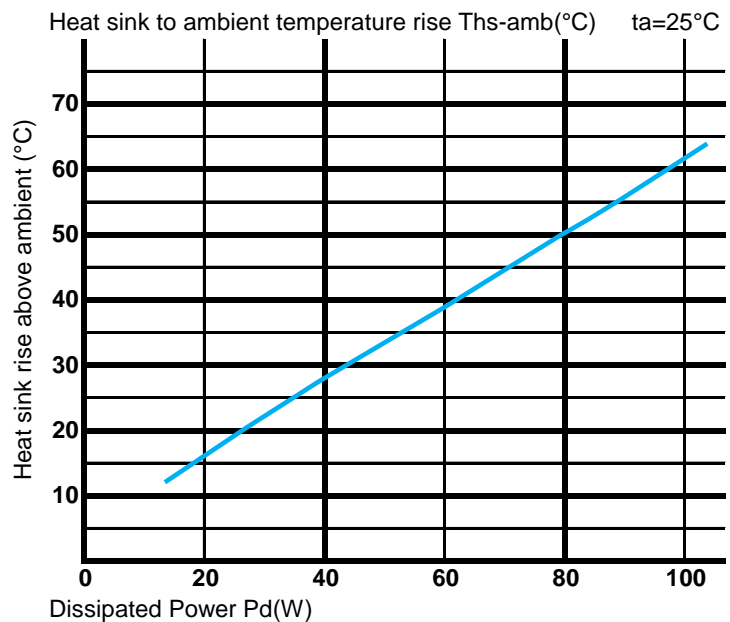
### The thermal data table

\* Please be aware the dissipated power  $P_d$  is not the same as the electrical power  $P_e$  of a LED module.

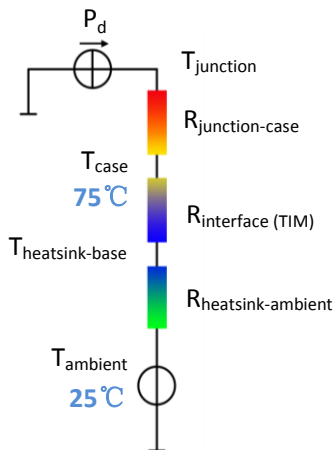
\*To calculate the dissipated power please use the following formula:  $P_d = P_e \times (1 - \eta_L)$ .

$P_d$  - Dissipated power ;  $P_e$  - Electrical power ;  $\eta_L$  = Light efficiency of the LED module;

Dissipated Power $P_d$ (W)	$P_d = P_e \times (1 - \eta_L)$	Heat sink to ambient thermal resistance $R_{hs-amb}$ ( $^{\circ}\text{C}/\text{W}$ )	Heat sink to ambient temperature rise $T_{hs-amb}$ ( $^{\circ}\text{C}$ )
		xLED-22530	
20.0		0.80	16.0
40.0		0.70	28.0
60.0		0.65	39.0
80.0		0.63	50.0
100.0		0.61	61.0



\*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface). MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



\*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different.

Formula:  $\theta = (T_{hs} - T_a) / P_d$

$\theta$  - Thermal Resistance [ $^{\circ}\text{C}/\text{W}$ ];  $T_{hs}$  - Heatsink temperature ;  $T_a$  - Ambient

\*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is  $R_{junction-case}$ , the thermal of the TIM outside the package is  $R_{interface (TIM)}$  [ $^{\circ}\text{C}/\text{W}$ ], the thermal resistance with heat sink is  $R_{heatsink-ambient}$  [ $^{\circ}\text{C}/\text{W}$ ], and the ambient temperature is  $T_{ambient}$  [ $^{\circ}\text{C}$ ].

\*Thermal resistances outside the package  $R_{interface (TIM)}$  and  $R_{heatsink-ambient}$  can be into the thermal resistance  $R_{case-ambient}$  at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot P_d + T_{ambient}$$